

ABSTRACT

The present invention relates to a polishing head for pressing a polishing tape against a substrate, such as a wafer. The present invention further relates to a polishing apparatus for polishing a substrate with such a polishing head. The polishing head (10) includes: a pressing member (12) configured to press a polishing tape (2) against the substrate (W); an actuator (15) configured to move the pressing member (12) in a predetermined pressing direction (CL) and apply a pressing force to the pressing member (12); and a tilt adjustment mechanism (40) configured to adjust tilt of the pressing member (12) with respect to the pressing direction (CL). The tilt adjustment mechanism (40) is configured to tilt the pressing member (12) with respect to the pressing direction (CL) and maintain an angle of the tilted pressing member (12).

FIG. 6